



Semiconductor Device Type: AEZC (RPX) 036 VQFN 6x6x0.9 Matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3																						
Basic Substance	CAS Number	Contained In Sub-Component	% Total Weight	mg/part	ppm	26.10 (mg) Total	Mold Compound	% of Total Weight	17.33																							
Silica, vitreous (or fused)	60676-86-0	Mold Compound	14.731	22.184	147,305	<table border="1"> <tr><td>Silica, vitreous (or fused)</td><td>60676-86-0</td><td>85.00</td></tr> <tr><td>Epoxy Resin</td><td>Trade Secret</td><td>8.70</td></tr> <tr><td>Phenolic Resin</td><td>Trade Secret</td><td>6.00</td></tr> <tr><td>Carbon Black</td><td>1333-86-4</td><td>0.30</td></tr> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Silica, vitreous (or fused)	60676-86-0	85.00	Epoxy Resin	Trade Secret	8.70	Phenolic Resin	Trade Secret	6.00	Carbon Black	1333-86-4	0.30	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00			
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Epoxy Resin	Trade Secret	Mold Compound	1.508	2.271	15,077																											
Phenolic Resin	Trade Secret	Mold Compound	1.040	1.566	10,398																											
Carbon Black	1333-86-4	Mold Compound	0.052	0.078	520																											
Copper	7440-50-8	Lead Frame	72.322	108.917	723,219																											
Iron	7439-89-6	Lead Frame	1.779	2.679	17,790	114.00 (mg) Total	Lead Frame	% of Total Weight	75.70																							
Silver	7440-22-4	Lead Frame	1.442	2.172	14,421	<table border="1"> <tr><td>Copper</td><td>7440-50-8</td><td>95.54</td></tr> <tr><td>Iron</td><td>7439-89-6</td><td>2.35</td></tr> <tr><td>Silver</td><td>7440-22-4</td><td>1.91</td></tr> <tr><td>Zinc</td><td>7440-66-6</td><td>0.13</td></tr> <tr><td>Phosphorous</td><td>7723-14-0</td><td>0.08</td></tr> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Copper	7440-50-8	95.54	Iron	7439-89-6	2.35	Silver	7440-22-4	1.91	Zinc	7440-66-6	0.13	Phosphorous	7723-14-0	0.08	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00
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Zinc	7440-66-6	Lead Frame	0.095	0.143	946																											
Phosphorous	7723-14-0	Lead Frame	0.062	0.094	625																											
Silver	7440-22-4	Die Attach	0.143	0.215	1,425																											
Epoxy resin	Trade Secret	Die Attach	0.048	0.072	475																											
Silicon	7440-21-3	Chip (Die)	4.210	6.340	42,100	0.29 (mg) Total	Die Attach	% of Total Weight	0.19																							
Copper	7440-57-5	Wire Bond	0.764	1.151	7,644	<table border="1"> <tr><td>Silver</td><td>7440-22-4</td><td>75.00</td></tr> <tr><td>Epoxy resin</td><td>Trade Secret</td><td>25.00</td></tr> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Silver	7440-22-4	75.00	Epoxy resin	Trade Secret	25.00	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00									
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Palladium	7440-05-3	Wire Bond	0.016	0.023	156																											
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.790	2.696	17,900	6.34 (mg) Total	Chip (Die)	% of Total Weight	4.21																							
0.1506 g Total Mass						<table border="1"> <tr><td>Doped Silicon</td><td>7440-21-3</td><td>100.00</td></tr> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Doped Silicon	7440-21-3	100.00	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00												
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This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)						1.17 (mg) Total	Wire Bond	% of Total Weight	0.78																							
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.						<table border="1"> <tr><td>Copper</td><td>7440-50-8</td><td>98.00</td></tr> <tr><td>Palladium</td><td>7440-05-3</td><td>2.00</td></tr> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Copper	7440-50-8	98.00	Palladium	7440-05-3	2.00	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00									
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If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.																																
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/						2.70 (mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.79																							
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.						<table border="1"> <tr><td>Tin</td><td>7440-31-5</td><td>100.00</td></tr> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Tin	7440-31-5	100.00	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00	<table border="1"> <tr><td colspan="2">Total</td><td>100.00</td></tr> </table>	Total		100.00												
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Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.																																
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table																																